DARPA Perspective

Dev Palmer, JUMP 2.0 Program Manager Jason Woo, JUMP 2.0 SUPREME PM Mentor Microsystems Technology Office

Briefing prepared for SUPREME Center Annual Review Ithaca, NY

August 2, 2023





Breakthrough technologies and capabilities for national security

Create breakthrough, paradigm-shifting solutions

Accept and manage significant technology risk

Disrupt or massively accelerate technology roadmaps





MTO Thrust

DISRUPTIVE MICROSYSTEMS

ERI 2.0 Focus Area

TALK Securing communications



COMPUTE Increasing information processing efficiency at the edge

DECIDE Accelerating innovation in AI hardware

BUILD Manufacturing complex 3D microsystems



SECURE Overcoming security threats across the entire hardware lifecycle

HARDEN Developing electronics for extreme environments

JUMP 2.0 Centers

CUBIC Center for Ubiquitous Connectivity

PRISM

Center for Processing with Intelligent Storage and Memory

COCOSYS

Center for the Co-Design of Cognitive Systems

CHIMES

Center for Heterogeneous Integration of Micro Electronic Systems

COGNISENSE

Center on Cognitive Multispectral Sensors

ACE

Evolvable Computing for Next-Generation Distributed Computer Systems

SUPREME Superior Energy-efficient Materials and Devices





DARPA PM Mentors will engage JUMP 2.0 centers

Attend yearly center reviews and SAB caucus discussions Interact with center researchers and industry liaisons Identify breakthrough ideas to seed DSSPs and new DARPA programs





John Davies EW/Adv. Processing



CUbiC

James Wilson Integration



Thomas Ehrenreich Directed Energy



Lok Yan Hardware Emulation





PRISM

Matt Wilding Software Engineering





Todd Bauer MEMS/Rad-Hard



JUMP 2.0 PM



Jason Woo CMOS/Processing

Dev Palmer
MTO Deputy Directo

PM	DARPA web bio
John Davies	https://www.darpa.mil/staff/mr-john-davies
James Wilson	https://www.darpa.mil/staff/dr-james-wilson
Thomas Ehrenreich	https://www.darpa.mil/staff/dr-thomas-ehrenreich
Lok Yan	https://www.darpa.mil/staff/dr-lok-yan

PM	DARPA web bio
Matt Wilding (I2O)	https://www.darpa.mil/staff/dr-matthew-wilding
Todd Bauer	https://www.darpa.mil/staff/dr-todd-bauer
Jason Woo	https://www.darpa.mil/staff/dr-jason-woo
Dev Palmer	https://www.darpa.mil/staff/dr-dev-palmer



CHIPS and Science Act

Forbes

BREAKING • BUSINESS

CHIPS Act Passes: House Approves \$280 Billion Bill To Boost Microchip Production And Counter China

Brian Bushard Forbes Staff *I cover breaking news for Forbes*

Jul 28, 2022, 03:26pm EDT

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NEWS SEMICONDUCTORS

U.S. Passes Landmark Act to Fund Semiconductor Manufacturing > CHIPS and Science Act of 2022 provides billions for new fabs and other incentives

BY SANUEL K. MOORE | 29 JUL 2022 | 3 MIN READ | []



Chip manufacturers are hoping their expansions will be less costly now. GETTY IMAGES



ERI 2.0: A long-term vision for advanced microelectronics manufacturing



Today

Time to Technology Implementation

Far-term



Program Manager (PM)

- Conceive, develop and execute complex research programs based on revolutionary ideas in advanced microsystems with high potential impact on national security
- Two-year initial appointment
 - Appointments may be extended up to a total of six years
- Various hiring vehicles
 - Term federal employee
 - Intergovernmental Personnel Act
 assignment
- Experienced professionals from academia, government, industry, and active duty military

https://www.darpa.mil/work-with-us/employment-at-darpa

Scientific, Engineering, and Technical Assistance (SETA)

- Support staff to DARPA PM
- Permanent contract position
- Technical (Tech SETA)
 - Key member of the program development team
 - Tracks technical milestones
 - Assists with proposal reviews
- Budget and Financial Management (BFM SETA)
 - Manages the PM's calendar and correspondence
 - Tracks program budgets
 - Organizes meetings and program reviews

Search "DARPA" on https://ecstech.com/careers/ and https://careers.boozallen.com/jobs/search

Innovation Fellow

- Develop and manage a portfolio of high-impact, exploratory efforts to identify breakthrough technologies
- Two-year position at DARPA for early career scientists and engineers
- Ph.D. graduates within five years of receiving a doctorate and active-duty military with STEM degree
- BS or MS-level candidates with STEM degrees in exceptional circumstances

https://www.darpa.mil/innovationfellowship

Candidates selected for positions at DARPA must be eligible to obtain a security clearance



DARPA opportunities outside of JUMP 2.0







Young Faculty Award (YFA)

- Identify and engage rising stars in junior research positions inside and outside of academia (see solicitation for eligibility details)
- \$250K/year for two years, possible \$500K Director's Fellowship in year three
- Solicitation typically published in August

Advanced Research Concepts (ARC)

- Focus on the rapid exploration and analysis of a high volume of promising new ideas
- One FTE for one year up to \$300K
- Program announcement DARPA-EA-23-01; periodic topic announcements with rolling six-month deadlines

DARPAConnect

- Broaden DARPA's reach and stimulate growth and collaboration with small businesses and educational institutions new to the national security space
- Hold pop-up events in a few cities around the country along with education opportunities, workshops, a mentor/ambassador component, and other outreach efforts
- Join the contact list at darpaconnect@darpa.mil and stay up-to-date on related opportunities, activities, and events

https://www.darpa.mil/work-with-us/for-universities/young-faculty-award https://www.darpa.mil/ARC https://www.darpa.mil/work-with-us/darpaconnect





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Innovation and impact

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